

## LOW SKEW, 1-TO-12 DIFFERENTIAL-TO-LVCMOS/LVTTL FANOUT BUFFER

ICS83948I-147

# **General Description**



The ICS83948I-147 is a low skew, 1-to-12
Differential-to-LVCMOS/LVTTL Fanout Buffer and a member of the HiPerClockS™family of High
Performance Clock Solutions from IDT. The
ICS83948I-147 has two selectable clock inputs. The

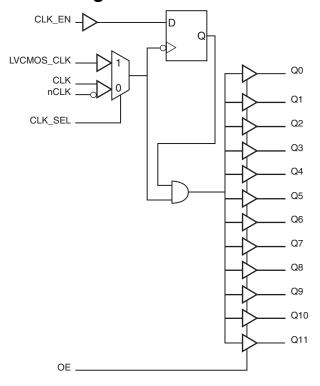
CLK, nCLK pair can accept most standard differential input levels. The LVCMOS\_CLK can accept LVCMOS or LVTTL input levels. The low impedance LVCMOS/LVTTL outputs are designed to drive  $50\Omega$  series or parallel terminated transmission lines. The effective fanout can be increased from 12 to 24 by utilizing the ability of the outputs to drive two series terminated lines.

The ICS83948I-147 is characterized at full 3.3V, full 2.5V or mixed 3.3V core/2.5V output operating supply modes. Guaranteed output and part-to-part skew characteristics make the ICS83948I-147 ideal for those clock distribution applications demanding well defined performance and repeatability.

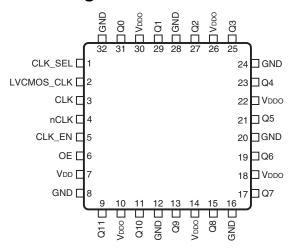
#### **Features**

- Twelve LVCMOS/LVTTL outputs
- Selectable differential CLK/nCLK or LVCMOS/LVTTL clock input
- CLK/nCLK pair can accept the following differential input levels: LVPECL, LVDS, LVHSTL, SSTL, HCSL
- LVCMOS\_CLK supports the following input types: LVCMOS, LVTTL
- Output frequency: 350MHz
- Additive phase jitter, RMS: 0.14ps (typical)
- Output skew: 100ps (maximum), 3.3V±5%
- Part-to-part skew: 1ns (maximum), 3.3V±5%
- · Operating supply modes:
- Core/Output 3.3V/3.3V 3.3V/2.5V 2.5V/2.5V
- -40°C to 85°C ambient operating temperature
- Available in both standard (RoHS 5) and lead-free (RoHS 6) packages

## **Block Diagram**



# **Pin Assignment**



ICS83948I-147

32-Lead LQFP
7mm x 7mm x 1.4mm package body
Y Package
Top View

**Table 1. Pin Descriptions** 

Number	Name	T	уре	Description
1	CLK_SEL	Input	Pullup	Clock select input. When HIGH, selects LVCMOS_CLK input. When LOW, selects CLK/nCLK inputs. LVCMOS / LVTTL interface levels.
2	LVCMOS_CLK	Input	Pullup	Single-ended clock input. LVCMOS/LVTTL interface levels.
3	CLK	Input	Pullup	Non-inverting differential clock input.
4	nCLK	Input	Pulldown	Inverting differential clock input.
5	CLK_EN	Input	Pullup	Clock enable pin. LVCMOS/LVTTL interface levels.
6	OE	Input	Pullup	Output enable pin. When LOW, outputs are in an High-impedance state. when HIGH, outputs are active. LVCMOS/LVTTL interface levels.
7	$V_{DD}$	Power		Power supply pin.
8, 12, 16, 20, 24, 28, 32	GND	Power		Power supply ground.
9, 11, 13, 15, 17, 19, 21, 23, 25, 27, 29, 31	Q11, Q10, Q9, Q8, Q7, Q6, Q5, Q4, Q3, Q2, Q1, Q0	Output		Single-ended clock outputs. LVCMOS/LVTTL interface levels.
10, 14, 18, 22, 26, 30	V <sub>DD</sub>	Power		Output supply pins.

NOTE: Pullup and Pulldown refer to internal input resistors. See Table 2, Pin Characteristics, for typical values.

# **Table 2. Pin Characteristics**

Symbol	Parameter	Test Conditions	Minimum	Typical	Maximum	Units
C <sub>IN</sub>	Input Capacitance			4		pF
R <sub>PULLUP</sub>	Input Pullup Resistor			51		kΩ
R <sub>PULLDOWN</sub>	Input Pulldown Resistor			51		kΩ
C <sub>PD</sub>	Power Dissipation Capacitance (per output)			12		pF
R <sub>OUT</sub>	Output Impedance		5	7	12	Ω

## **Function Tables**

### **Table 3A. Clock Select Function Table**

Control Input	Clock
0	CLK/nCLK inputs selected
1	LVCMOS_CLK input selected

**Table 3B. Clock Input Function Table** 

		Inputs		Outputs		
CLK_SEL	LVCMOS_CLK	CLK	nCLK	Q[0:11]	Input to Output Mode	Polarity
0	-	0	1	LOW	Differential to Single-Ended	Non-Inverting
0	-	1	0	HIGH	Differential to Single-Ended	Non-Inverting
0	_	0	Biased; NOTE 1	LOW	Single-Ended to Single-Ended	Non-Inverting
0	_	1	Biased; NOTE 1	HIGH	Single-Ended to Single-Ended	Non-Inverting
0	-	Biased; NOTE 1	0	HIGH	Single-Ended to Single-Ended	Inverting
0	_	Biased; NOTE 1	1	LOW	Single-Ended to Single-Ended	Inverting
1	0	-	-	LOW	Single-Ended to Single-Ended	Non-Inverting
1	1	_	_	HIGH	Single-Ended to Single-Ended	Non-Inverting

NOTE 1: Please refer to the Application Information Section, Wiring the Differential Input to Accept Single-ended Levels.

# **Absolute Maximum Ratings**

NOTE: Stresses beyond those listed under *Absolute Maximum Ratings* may cause permanent damage to the device. These ratings are stress specifications only. Functional operation of product at these conditions or any conditions beyond those listed in the *DC Characteristics* or *AC Characteristics* is not implied. Exposure to absolute maximum rating conditions for extended periods may affect product reliability.

Item	Rating
Supply Voltage, V <sub>DD</sub>	4.6V
Inputs, V <sub>I</sub>	-0.5V to V <sub>DD</sub> + 0.5V
Outputs, V <sub>O</sub>	-0.5V to V <sub>DDO</sub> + 0.5V
Package Thermal Impedance, $\theta_{JA}$	73.6°C/W (0 mps)
Storage Temperature, T <sub>STG</sub>	-65°C to 150°C

#### **DC Electrical Characteristics**

Table 4A. Power Supply DC Characteristics,  $V_{DD} = V_{DDO} = 3.3V \pm 5\%$ ,  $T_A = -40$ °C to 85°C

Symbol	Parameter	Test Conditions	Minimum	Typical	Maximum	Units
$V_{DD}$	Power Supply Voltage		3.135	3.3	3.465	V
$V_{DDO}$	Output Supply Voltage		3.135	3.3	3.465	V
I <sub>DD</sub>	Power Supply Current				55	mA

Table 4B. Power Supply DC Characteristics,  $V_{DD} = V_{DDO} = 2.5V \pm 5\%$ ,  $T_A = -40^{\circ}C$  to  $85^{\circ}C$ 

Symbol	Parameter	Test Conditions	Minimum	Typical	Maximum	Units
$V_{DD}$	Positive Supply Voltage		2.375	2.5	2.625	V
$V_{DDO}$	Output Supply Voltage		2.375	2.5	2.625	V
$I_{DD}$	Power Supply Current				52	mA

Table 4C. Power Supply DC Characteristics,  $V_{DD} = 3.3V \pm 5\%$ ,  $V_{DDO} = 2.5V \pm 5\%$ ,  $T_A = -40^{\circ}C$  to  $85^{\circ}C$ 

Symbol	Parameter	Test Conditions	Minimum	Typical	Maximum	Units
$V_{DD}$	Power Supply Voltage		3.135	3.3	3.465	٧
$V_{DDO}$	Output Supply Voltage		2.375	2.5	2.625	V
I <sub>DD</sub>	Power Supply Current				55	mA

## Table 4D. DC Characteristics, $T_A = -40$ °C to 85°C

Symbol	Parameter		Test Conditions	Minimum	Typical	Maximum	Units
V	Input High Voltage	LVCMOS	V <sub>DD</sub> = 3.465V	2		V <sub>DD</sub> + 0.3	V
V IH	$V_{IH} = \begin{array}{c} \text{Input High Voltage} \\ V_{IH} = \begin{array}{c} \text{Input High Voltage} \\ \end{array} & \begin{array}{c} \text{LVCMOS} \\ \text{LVCMOS} \\ \end{array} & \begin{array}{c} V_{DD} = 3.465 \text{V} \\ \end{array} & \begin{array}{c} 2 \\ \text{1.7} \\ \end{array} \\ V_{IL} = \begin{array}{c} \text{Input Low Voltage} \\ \end{array} & \begin{array}{c} \text{LVCMOS} \\ \end{array} & \begin{array}{c} V_{DD} = 3.465 \text{V} \\ \end{array} & \begin{array}{c} -0.3 \\ \end{array} \\ \end{array} \\ V_{IN} = V_{DD} \text{ or } V_{IN} = 3.465 \text{V} \\ \text{ or } 2.625 \text{V} \\ \end{array} & \begin{array}{c} -0.3 \\ \end{array} \\ V_{IN} = V_{DD} \text{ or } V_{IN} = 3.465 \text{V} \\ \text{ or } 2.625 \text{V} \\ \end{array} & \begin{array}{c} 0.3 \\ \end{array} \\ V_{DDO} = 3.3 \text{V} \pm 5\% \\ I_{OH} = -24 \text{mA} \\ \end{array} & \begin{array}{c} 2.4 \\ \end{array} \\ V_{DDO} = 2.5 \text{V} \pm 5\% \\ I_{OL} = 24 \text{mA} \\ \end{array} & \begin{array}{c} V_{DDO} = 3.3 \text{V} \pm 5\% \\ I_{OL} = 24 \text{mA} \\ \end{array} \\ V_{DDO} = 3.3 \text{V} \pm 5\% \\ I_{OL} = 12 \text{mA} \\ \end{array} & \begin{array}{c} V_{DDO} = 2.5 \text{V} \pm 5\% \\ I_{OL} = 12 \text{mA} \\ \end{array} \\ V_{DDO} = 2.5 \text{V} \pm 5\% \\ I_{OL} = 15 \text{mA} \\ \end{array} & \begin{array}{c} V_{DDO} = 2.5 \text{V} \pm 5\% \\ I_{OL} = 15 \text{mA} \\ \end{array} \\ \end{array} \\ \begin{array}{c} V_{DDO} = 2.5 \text{V} \pm 5\% \\ I_{OL} = 15 \text{mA} \\ \end{array} \\ \end{array} \\ \begin{array}{c} V_{DDO} = 2.5 \text{V} \pm 5\% \\ I_{OL} = 15 \text{mA} \\ \end{array} $	1.7		V <sub>DD</sub> + 0.3	٧		
V	Input Low Voltago	LVCMOS	V <sub>DD</sub> = 3.465V	-0.3		0.8	V
VIL.	-	LVCMOS	V <sub>DD</sub> = 2.625V	-0.3		0.7	٧
I <sub>IN</sub>	Input Current					300	μA
V	Output High Voltage NOTE 1			2.4			V
VOH	Output High Voltage, NOTE 1			1.8			V
						0.55	V
$V_{OL}$	Output Low Voltage; NOTE 1					0.30	V
						0.6	V
V <sub>PP</sub>		CLK/nCLK	V <sub>DD</sub> = 3.465V or 2.625V	0.15		1.3	V
V <sub>CMR</sub>	Common Mode Input Voltage; NOTE 2, 3	CLK/nCLK	V <sub>DD</sub> = 3.465V or 2.625V	GND + 0.5		V <sub>DD</sub> – 0.85	V

NOTE 1: Outputs capable of driving 50 $\Omega$  transmission lines terminated with 50 $\Omega$  to V<sub>DDO</sub>/2.

See Parameter Measurement section, Output Load AC Test Circuit diagrams.

NOTE 2: V<sub>IL</sub> should not be less than -0.3V.

NOTE 3: Common mode voltage is defined as V<sub>IH</sub>.

### **AC Electrical Characteristics**

Table 5A. AC Characteristics,  $V_{DD} = V_{DDO} = 3.3V \pm 5\%$ ,  $T_A = -40^{\circ}C$  to  $85^{\circ}C$ 

Parameter	Symbol		Test Conditions	Minimum	Typical	Maximum	Units
f <sub>MAX</sub>	Output Frequency					350	MHz
		CLK/nCLK; NOTE 1	<i>f</i> ≤ 350MHz	2		4	ns
t <sub>PD</sub>	Propagation Delay	LVCMOS_CLK; NOTE 2	<i>f</i> ≤ 350MHz	2		4	ns
<i>t</i> jit	Buffer Additive Phase Additive Phase Jitte	se Jitter, RMS; refer to r Section	155.52MHz, Integration Range: 12kHz – 20MHz		0.14	1	ps
tsk(o)	Output Skew; NOTE	3, 7	Measured on the Rising Edge @ V <sub>DDO</sub> /2			100	ps
tsk(pp)	Part-to-Part Skew; N	NOTE 4, 7	Measured on the Rising Edge @ V <sub>DDO</sub> /2			1	ns
t <sub>R</sub> / t <sub>F</sub>	Output Rise/Fall Tim	ne	0.8V to 2V	0.2		1.0	ns
odc	Output Duty Cycle		$f \le 150$ MHz, Ref = CLK/nCLK	45	50	55	%
t <sub>PZL</sub> , t <sub>PZH</sub>	Output Enable Time	; NOTE 5				5	ns
t <sub>PLZ</sub> , t <sub>PHZ</sub>	Output Disable Time	e; NOTE 5				5	ns
	Clock Enable	CLK_EN to CLK/nCLK		1			ns
t <sub>S</sub>	Setup Time; NOTE 6	CLK_EN to LVCMOS_CLK		0			ns
	Clock Enable	CLK/nCLK to CLK_EN		0			ns
t <sub>H</sub>	Hold Time; NOTE 6	LVCMOS_CLK to CLK_EN		1			ns

NOTE: Electrical parameters are guaranteed over the specified ambient operating temperature range, which is established when the device is mounted in a test socket with maintained transverse airflow greater than 500 lfpm. The device will meet specifications after thermal equilibrium has been reached under these conditions.

- NOTE 1: Measured from the differential input crossing point to V<sub>DDO</sub>/2 of the output.
- NOTE 2: Measured from  $V_{DD}/2$  of the input to  $V_{DDO}/2$  of the output.
- NOTE 3: Defined as skew between outputs at the same supply voltage and with equal load conditions. Measured at V<sub>DDO</sub>/2.
- NOTE 4: Defined as skew between outputs on different devices operating at the same supply voltage and with equal load conditions. Using the same type of input on each device, the output is measured at  $V_{DDO}/2$ .
- NOTE 5: These parameters are guaranteed by characterization. Not tested in production.
- NOTE 6: Setup and Hold times are relative to the rising edge of the input clock.
- NOTE 7: This parameter is defined in accordance with JEDEC Standard 65.

Table 5B. AC Characteristics,  $V_{DD} = V_{DDO} = 2.5V \pm 5\%$ ,  $T_A = -40$ °C to 85°C

Parameter	Symbol		Test Conditions	Minimum	Typical	Maximum	Units
f <sub>MAX</sub>	Output Frequency					350	MHz
		CLK/nCLK; NOTE 1	<i>f</i> ≤ 350MHz	1.5		4.2	ns
t <sub>PD</sub>	Propagation Delay	LVCMOS_CLK; NOTE 2	<i>f</i> ≤ 350MHz	1.7		4.4	ns
<i>t</i> jit	Buffer Additive Phas Additive Phase Jitter	se Jitter, RMS; refer to r Section	155.52MHz, Integration Range: 12kHz – 20MHz		0.14	1	ps
tsk(o)	Output Skew; NOTE	E 3, 7	Measured on the Rising Edge @ V <sub>DDO</sub> /2			160	ps
tsk(pp)	Part-to-Part Skew; N	NOTE 4, 7	Measured on the Rising Edge @ V <sub>DDO</sub> /2			2	ns
t <sub>R</sub> / t <sub>F</sub>	Output Rise/Fall Tim	ne	0.6V to 1.8V	0.1		1.0	ns
odc	Output Duty Cycle		$f \le 150$ MHz, Ref = CLK/nCLK	40		60	%
t <sub>PZL</sub> , t <sub>PZH</sub>	Output Enable Time	; NOTE 5				5	ns
t <sub>PLZ</sub> , t <sub>PHZ</sub>	Output Disable Time	e; NOTE 5				5	ns
	Clock Enable	CLK_EN to CLK/nCLK		1			ns
t <sub>S</sub>	Setup Time; NOTE 6	CLK_EN to LVCMOS_CLK		0			ns
	Clock Enable	CLK/nCLK to CLK_EN		0			ns
t <sub>H</sub>	Hold Time; NOTE 6	LVCMOS_CLK to CLK_EN		1			ns

NOTE: Electrical parameters are guaranteed over the specified ambient operating temperature range, which is established when the device is mounted in a test socket with maintained transverse airflow greater than 500 lfpm. The device will meet specifications after thermal equilibrium has been reached under these conditions.

- NOTE 1: Measured from the differential input crossing point to  $V_{DDO}/2$  of the output.
- NOTE 2: Measured from  $V_{DD}/2$  of the input to  $V_{DDO}/2$  of the output.
- NOTE 3: Defined as skew between outputs at the same supply voltage and with equal load conditions. Measured at V<sub>DDO</sub>/2.
- NOTE 4: Defined as skew between outputs on different devices operating at the same supply voltage and with equal load conditions. Using the same type of input on each device, the output is measured at  $V_{\rm DDO}/2$ .
- NOTE 5: These parameters are guaranteed by characterization. Not tested in production.
- NOTE 6: Setup and Hold times are relative to the rising edge of the input clock.
- NOTE 7: This parameter is defined in accordance with JEDEC Standard 65.

Table 5C. AC Characteristics,  $V_{DD} = 3.3V \pm 5\%$ ,  $V_{DDO} = 2.5V \pm 5\%$ ,  $T_A = -40$ °C to 85°C

Parameter	Symbol		Test Conditions	Minimum	Typical	Maximum	Units
f <sub>MAX</sub>	Output Frequency					350	MHz
		CLK/nCLK; NOTE 1	<i>f</i> ≤ 350MHz	2		4	ns
t <sub>PD</sub>	Propagation Delay	LVCMOS_CLK; NOTE 2	<i>f</i> ≤ 350MHz	2		4	ns
<i>t</i> jit	Buffer Additive Phas Additive Phase Jitter	se Jitter, RMS; refer to r Section	155.52MHz, Integration Range: 12kHz – 20MHz		0.14	1	ps
tsk(o)	Output Skew; NOTE	3, 7	Measured on the Rising Edge @ V <sub>DDO</sub> /2			100	ps
tsk(pp)	Part-to-Part Skew; N	NOTE 4, 7	Measured on the Rising Edge @ V <sub>DDO</sub> /2			1	ns
t <sub>R</sub> / t <sub>F</sub>	Output Rise/Fall Tim	ne	0.8V to 2V	0.1		1.0	ns
odc	Output Duty Cycle		$f \le 200$ MHz, Ref = CLK/nCLK	45		55	%
t <sub>PZL</sub> , t <sub>PZH</sub>	Output Enable Time	; NOTE 5				5	ns
t <sub>PLZ</sub> , t <sub>PHZ</sub>	Output Disable Time	e; NOTE 5				5	ns
	Clock Enable	CLK_EN to CLK/nCLK		1			ns
t <sub>S</sub>	Setup Time; NOTE 6	CLK_EN to LVCMOS_CLK		0			ns
	Clock Enable	CLK/nCLK to CLK_EN		0			ns
t <sub>H</sub>	Hold Time; NOTE 6	LVCMOS_CLK to CLK_EN		1			ns

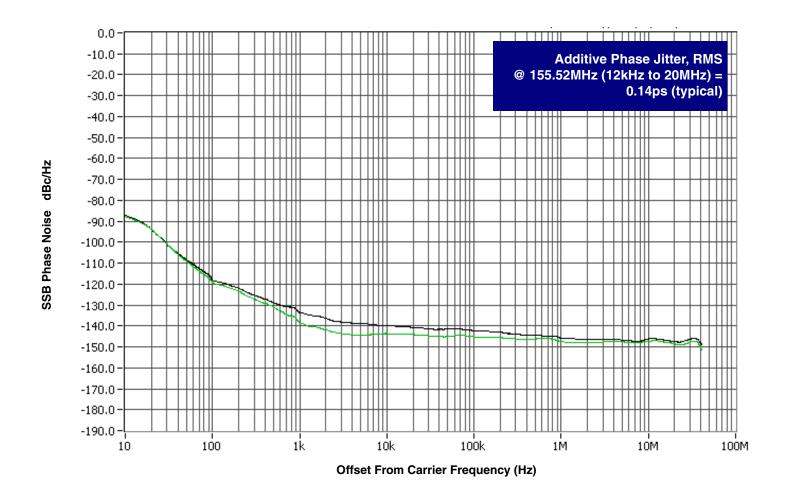
NOTE: Electrical parameters are guaranteed over the specified ambient operating temperature range, which is established when the device is mounted in a test socket with maintained transverse airflow greater than 500 lfpm. The device will meet specifications after thermal equilibrium has been reached under these conditions.

- NOTE 1: Measured from the differential input crossing point to  $V_{DDO}/2$  of the output.
- NOTE 2: Measured from  $V_{DD}/2$  of the input to  $V_{DDO}/2$  of the output.
- NOTE 3: Defined as skew between outputs at the same supply voltage and with equal load conditions. Measured at V<sub>DDO</sub>/2.
- NOTE 4: Defined as skew between outputs on different devices operating at the same supply voltage and with equal load conditions. Using the same type of input on each device, the output is measured at  $V_{\rm DDO}/2$ .
- NOTE 5: These parameters are guaranteed by characterization. Not tested in production.
- NOTE 6: Setup and Hold times are relative to the rising edge of the input clock.
- NOTE 7: This parameter is defined in accordance with JEDEC Standard 65.

#### **Additive Phase Jitter**

The spectral purity in a band at a specific offset from the fundamental compared to the power of the fundamental is called the *dBc Phase Noise*. This value is normally expressed using a Phase noise plot and is most often the specified plot in many applications. Phase noise is defined as the ratio of the noise power present in a 1Hz band at a specified offset from the fundamental frequency to the power value of the fundamental. This ratio is expressed in decibels (dBm) or a ratio of the power in the 1Hz band

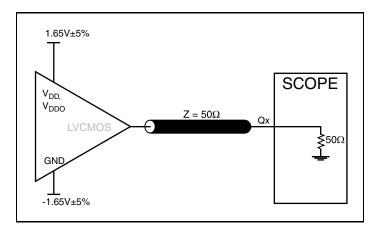
to the power in the fundamental. When the required offset is specified, the phase noise is called a *dBc* value, which simply means dBm at a specified offset from the fundamental. By investigating jitter in the frequency domain, we get a better understanding of its effects on the desired application over the entire time record of the signal. It is mathematically possible to calculate an expected bit error rate given a phase noise plot.



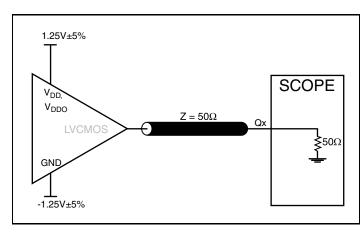
As with most timing specifications, phase noise measurements has issues relating to the limitations of the equipment. Often the noise floor of the equipment is higher than the noise floor of the

device. This is illustrated above. The device meets the noise floor of what is shown, but can actually be lower. The phase noise is dependent on the input source and measurement equipment.

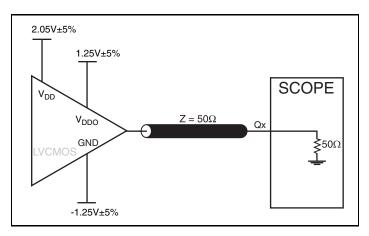
## **Parameter Measurement Information**



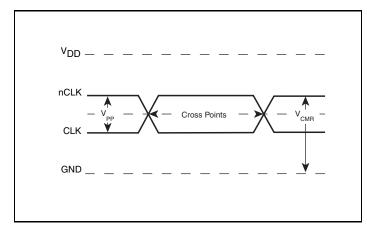
3.3V Core/3.3V LVCMOS Output Load AC Test Circuit



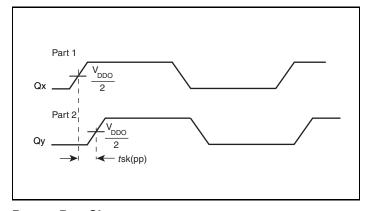
2.5V Core/2.5V LVCMOS Output Load AC Test Circuit



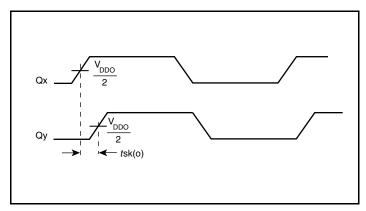
3.3V Core/2.5V LVCMOS Output Load AC Test Circuit



**Differential Input Level** 

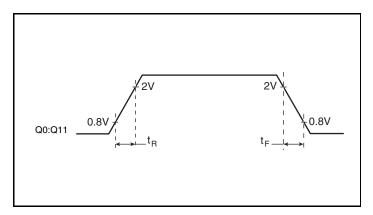


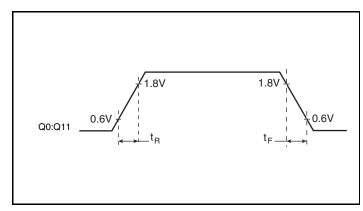
Part-to-Part Skew



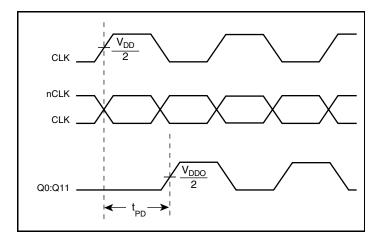
**Output Skew** 

# **Parameter Measurement Information, continued**

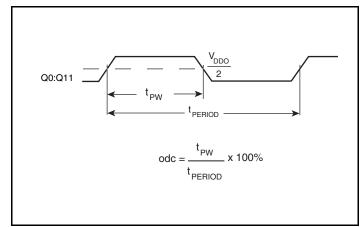




#### 3.3V Output Rise/Fall Time



2.5V Output Rise/Fall Time



**Propagation Delay** 

**Output Duty Cycle/Pulse Width/Period** 

## **Application Information**

## Wiring the Differential Input to Accept Single Ended Levels

Figure 1 shows how the differential input can be wired to accept single ended levels. The reference voltage V\_REF =  $V_{DD}/2$  is generated by the bias resistors R1, R2 and C1. This bias circuit should be located as close as possible to the input pin. The ratio of R1 and R2 might need to be adjusted to position the V\_REF in the center of the input voltage swing. For example, if the input clock swing is only 2.5V and  $V_{DD} = 3.3V$ , V\_REF should be 1.25V and R2/R1 = 0.609.

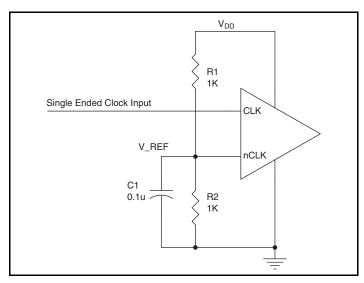


Figure 1. Single-Ended Signal Driving Differential Input

### **Recommendations for Unused Input and Output Pins**

# Inputs:

#### **CLK/nCLK Inputs**

For applications not requiring the use of the differential input, both CLK and nCLK can be left floating. Though not required, but for additional protection, a  $1k\Omega$  resistor can be tied from CLK to ground.

#### **CLK Input**

For applications not requiring the use of a clock input, it can be left floating. Though not required, but for additional protection, a  $1k\Omega$  resistor can be tied from the CLK input to ground.

#### **LVCMOS Control Pins**

All control pins have internal pull-ups or pull-downs; additional resistance is not required but can be added for additional protection. A  $1k\Omega$  resistor can be used.

## **Outputs:**

#### **LVCMOS Outputs**

All unused LVCMOS output can be left floating. There should be no trace attached.

#### **Differential Clock Input Interface**

The CLK /nCLK accepts LVDS, LVPECL, LVHSTL, SSTL, HCSL and other differential signals. Both signals must meet the  $V_{PP}$  and  $V_{CMR}$  input requirements. Figures 2A to 2F show interface examples for the HiPerClockS CLK/nCLK input driven by the most common driver types. The input interfaces suggested here are examples only. Please consult with the vendor of the driver

component to confirm the driver termination requirements. For example, in Figure 2A, the input termination applies for IDT HiPerClockS open emitter LVHSTL drivers. If you are using an LVHSTL driver from another vendor, use their termination recommendation.

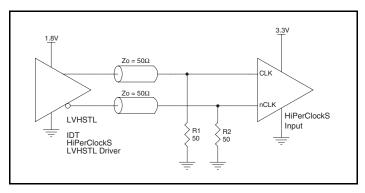


Figure 2A. HiPerClockS CLK/nCLK Input
Driven by an IDT Open Emitter
HiPerClockS LVHSTL Driver

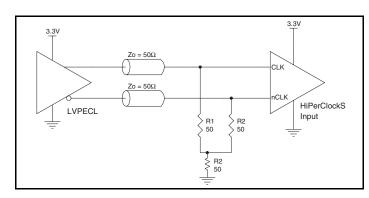


Figure 2B. HiPerClockS CLK/nCLK Input
Driven by a 3.3V LVPECL Driver

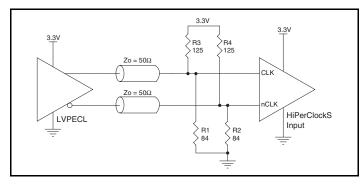


Figure 2C. HiPerClockS CLK/nCLK Input
Driven by a 3.3V LVPECL Driver

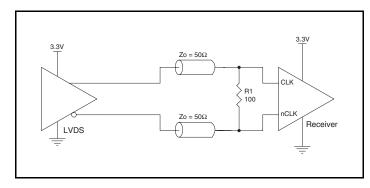


Figure 2D. HiPerClockS CLK/nCLK Input Driven by a 3.3V LVDS Driver

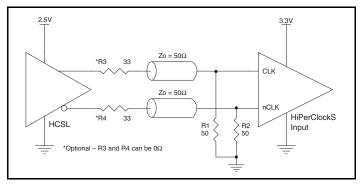


Figure 2E. HiPerClockS CLK/nCLK Input Driven by a 3.3V HCSL Driver

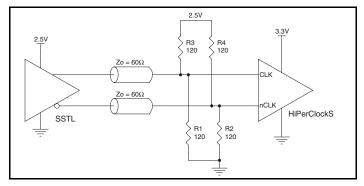


Figure 2F. HiPerClockS CLK/nCLK Input Driven by a 2.5V SSTL Driver

# **Reliability Information**

## Table 6. $\theta_{\text{JA}}$ vs. Air Flow Table for a 32 Lead LQFP

$ heta_{\sf JA}$ vs. Air Flow					
Meters per Second	0	1	2.5		
Multi-Layer PCB, JEDEC Standard Test Boards	73.6°C/W	63.9°C/W	60.3°C/W		

## **Transistor Count**

The transistor count for ICS83948I-147 is: 1040 Pin compatible with the MPC9448

# **Package Outline and Package Dimension**

Package Outline - Y Suffix for 32 Lead LQFP

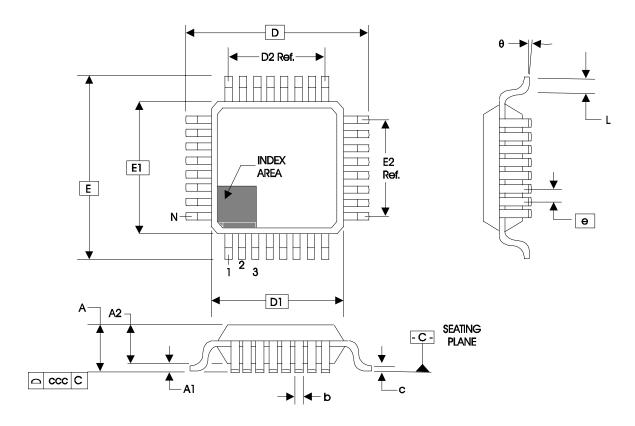


Table 7. Package Dimensions for 32 Lead LQFP

JEDEC Variation: ABC - HD All Dimensions in Millimeters				
Symbol	Minimum	Nominal	Maximum	
N	32			
Α			1.60	
A1	0.05	0.10	0.15	
A2	1.35	1.40	1.45	
b	0.30	0.37	0.45	
С	0.09		0.20	
D&E		9.00 Basic		
D1 & E1	7.00 Basic			
D2 & E2	5.60 Ref.			
е	0.80 Basic			
L	0.45	0.60	0.75	
θ	0°		7°	
ccc			0.10	

Reference Document: JEDEC Publication 95, MS-026

# **Ordering Information**

#### **Table 8. Ordering Information**

Part/Order Number	Marking	Package	Shipping Packaging	Temperature
83948AYI-147	ICS83948AI147	32 Lead LQFP	Tray	-40°C to 85°C
83948AYI-147T	ICS83948AI147	32 Lead LQFP	1000 Tape & Reel	-40°C to 85°C
83948AYI-147LF	ICS948AI147L	"Lead-Free" 32 Lead LQFP	Tray	-40°C to 85°C
83948AYI-147ILFT	ICS948AI147L	"Lead-Free" 32 Lead LQFP	1000 Tape & Reel	-40°C to 85°C

NOTE: Parts that are ordered with an "LF" suffix to the part number are the Pb-Free configuration and are RoHS compliant.

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# **Revision History Sheet**

Rev	Table	Page	Description of Change	Date
В	T2 T8	1 2 7 10	Features Section - added Lead-Free bullet. Pin Characteristics Table - changed $C_{\text{IN}}$ from 4pF max. to 4pF typical; and added $5\Omega$ min. and $12\Omega$ max to $R_{\text{OUT}}$ . Updated Single Ended Signal Driving Differential Input diagram. Added Recommendations for Unused Input and Output Pins. Ordering Information Table - added lead-free part number, marking, and note.	11/21/05
С	T5A T5B T6	1 5 6 7 11 12	Features Section - added Additive Phase Jitter bullet. 3.3V AC Characteristics Table - added Additive Phase Jitter. 3.3V AC Characteristics Table - added Additive Phase Jitter. Added Additive Phase Jitter section. Updated Differential Input Clock Interface section. Updated Reliability Information. Updated format throughout the datasheet.	1/15/08
D	T4C T5C	1 4 7 9	Features Section - added mix voltage to supply voltage bullet.  Added Mix DC Characteristics Power Supply Table.  Added Mix AC Characteristics Table.  Parameter Measurement Information Section - added 3.3V/2.5V LVCMOS  Output Load AC Test Circuit diagram.  Ordering Information Table - deleted ICS prefix from Part/Order Number column.	4/1/09

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